
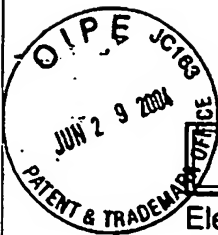


FORM PTO-1449		Atty. Docket No. ATM-302		Serial No. 10/817,619		
LIST OF PRIOR ART CITED BY APPLICANT						
		Applicant: Philip A. Rochette		#3105		
		Filing Date: April 1, 2004		Group: 2811		
U.S. PATENT DOCUMENTS						
Examiner Initial*	Document Number	Grant Date	Name	Class	Sub Class	Filing Date
AA						
AB						
AC						
AD						
AE						
AF						
AG						
AH						
AI						
AJ						
FOREIGN PATENT DOCUMENTS						
Examiner Initial*	Document Number	Grant Date	Country	Class	Sub Class	Translation Yes No
AK						
AL						
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)						
MSP	AM	S. Thomas et al., "Micro-Corrosion of Al-Cu Bonding Pads", IEEE Transactions on Components, Hybrids, and Manufacturing Technology, June 1987, Vol. CHMT-10, No. 2, pp. 252-257.				
MSP	AN	Printout: "Galvanic Voids, Semiconductor Reliability News, April 1992, 1 page.				
	AO					
EXAMINER: <i>Marcelo B. Siqueira</i>				DATE CONSIDERED: 7/11/2005		
<p>*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>						



#205
6/29/04

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of
Invention

METHOD AND APPARATUS TO ELIMINATE GALVANIC
CORROSION ON COPPER DOPED ALUMINUM BOND
PADS ON INTEGRATED CIRCUITS

Application Number: 10/817619
Confirmation Number: 2479
First Named Applicant: Philip Rochette
Attorney Docket Number: ATM-302
Art Unit: 2811
Search string: (4478915 or 20020081776).pn.



US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
MP	1	4478915	1984-10-23	Poss et al.	A1	428	607

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
MP	1	20020081776	2002-06-27	Tellkamp	A1	438	113

Signature

Examiner Name	Date
<i>Harold R. Lutz</i>	7/11/2005